

*SPECIFICATION AMENDMENTS*

Replace the paragraph beginning at page 1, line 11 with:

Generally, it is ~~examined before shipment~~ determined whether the semiconductor chips are faulty ~~i.e., have an "initial defect"~~, before their shipment (~~hereafter, "initial defect"~~). The initial defect may occur in the semiconductor chips in the manufacturing process. Only the good semiconductor chips, which pass this examination, are shipped. The inspection ~~of the~~ for initial defects of the semiconductor chips and malfunctions at the manufacturing steps of the semiconductor chips is conducted by a test called a "burn-in test". In this burn-in test, a semiconductor chip is put in a high temperature environment, e.g., 125 °C (degree centigrade), in which a voltage or a signal is applied to the semiconductor chip.